Filename: ProFC98.tmp

Variant: 001

Generated: 1/10/2018 12:32:28 PM

TD #: TIDA-01416



TIDA-01416 REV A Bill of Materials

Item #	Designator	Quantity	Value	PartNumber	Manufacturer	Description	PackageReference
1	!PCB	1		TIDA-01416	Any	Printed Circuit Board	
2	C1	1	150uF	T520B157M006ATE070	Kemet	CAP, TA, 150 μF, 6.3 V, +/- 20%, 0.07 ohm, SMD	3528-21
3	C2, C8, C14, C20, C26	5	10uF	GRM188R60J106ME84	MuRata	CAP, CERM, 10 µF, 6.3 V, +/- 20%, X5R, 0603	0603
4	C3, C9, C15, C21, C27	5	22pF	GRM1555C1H220FA01D	MuRata	CAP, CERM, 22 pF, 50 V, +/- 1%, C0G/NP0, 0402	0402
5	C4, C10, C16, C22, C28	5	470pF	GCM155R71H471KA37D	MuRata	CAP, CERM, 470 pF, 50 V, +/- 10%, X7R, AEC-Q200 Grade 1, 0402	0402
6	C5, C11, C17, C23, C29	5	2.2uF	GCM188C71A225K	MuRata	CAP, CERM, 2.2 μF, 10 V, +/- 10%, X7S, 0603	0603
7	C6, C7, C18, C19	4	22uF	GRM21BR61A226ME44L	MuRata	CAP, CERM, 22 µF, 10 V, +/- 20%, X5R, 0805	0805
8	C12, C13, C24, C25, C30, C31	6	22uF	GRM21BR60J226ME39L	MuRata	CAP, CERM, 22 μF, 6.3 V, +/- 20%, X5R, 0805	0805
9	H1, H2, H3, H4	4		NY PMS 440 0025 PH	B&F Fastener Supply	Machine Screw, Round, #4-40 x 1/4, Nylon, Philips panhead	Screw
10	H5, H6, H7, H8	4		1902C	Keystone	Standoff, Hex, 0.5"L #4-40 Nylon	Standoff
11	J1, J2, J5, J7, J9, J11	6		TSW-106-07-T-S	Samtec	Header, 100mil, 6x1, Tin, TH	6x1 Header
12	J3, J4, J6, J8, J10, J12, J13, J14	8		TSW-102-07-T-S	Samtec	Header, 2.54 mm, 2x1, Tin, TH	Header, 2.54 mm, 2x1, TH
13	JP1, JP2, JP3, JP4, JP5	5		TSW-103-07-T-S	Samtec	Header, 2.54 mm, 3x1, Tin, TH	Header, 2.54 mm, 3x1, TH
14	L1	1	470nH	XFL4015-471MEC	Coilcraft	Inductor, Shielded, Composite, 470 nH, 3.5 A, 0.0076 ohm, SMD	SMD, 4x4x1.5mm
15	L2, L3, L4, L5	4	1uH	XFL3012-102MEB	Coilcraft	Inductor, Shielded, Composite, 1 µH, 2.5 A, 0.04 ohm, SMD	3x1.2x3mm
16	R1	1)	RC0603FR-071ML	Yageo America	RES, 1.00 M, 1%, 0.1 W, 0603	0603
17	R2	1	63.4k	RT0603BRD0763K4L	Yageo America	RES, 63.4 k, 0.1%, 0.1 W, 0603	0603
18	R3	1	169k	RT0603BRD07169KL	Yageo America	RES, 169 k, 0.1%, 0.1 W, 0603	0603
19	R4, R9, R12, R13	4	178k	RC0603FR-07178KL	Yageo America	RES, 178 k, 1%, 0.1 W, 0603	0603
20	R5	1	118k	RT0603BRD07118KL	Yageo America	RES, 118 k, 0.1%, 0.1 W, 0603	0603
21	R6	1	39.2k	RC0603FR-0739K2L	Yageo America	RES, 39.2 k, 1%, 0.1 W, 0603	0603
22	R7	1	113k	CRCW0603113KFKEA	Vishay-Dale	RES, 113 k, 1%, 0.1 W, 0603	0603
23	R8	1	165k	RT0603BRD07165KL	Yageo America	RES, 165 k, 0.1%, 0.1 W, 0603	0603
24	R10	1	243k	RT0603BRD07243KL	Yageo America	RES, 243 k, 0.1%, 0.1 W, 0603	0603
25	R11	1	38.3k	RT0603BRD0738K3L	Yageo America	RES, 38.3 k, 0.1%, 0.1 W, 0603	0603
26	R14	1	243k	RC0603FR-07243KL	Yageo America	RES, 243 k, 1%, 0.1 W, 0603	0603
27	R15	1		RC0603FR-0738K3L	Yageo America	RES, 38.3 k, 1%, 0.1 W, 0603	0603
28	R16, R17, R18	3	100k	CRCW0603100KJNEA	Vishay-Dale	RES, 100 k, 5%, 0.1 W, 0603	0603
29	U1	1		TLV62085RLTR	Texas Instruments	3-A High Efficiency Synchronous Step-Down Converter, RLT0007A (VSON-HR-7)	RLT0007A
30	U2, U4, U5	3		TLV62080DSGR	Texas Instruments	1.2A High Efficient Step Down Converter in 2x2mm SON Package, DSG0008A (WSON-8)	DSG0008A
31	U3	1		TLV62084ADSGR	Texas Instruments	2A High Efficient Step Down Converter in 2x2mm SON Package, DSG0008A (WSON-8)	DSG0008A
32	U6	1		LM3880MF-1AA	Texas Instruments	Power Sequencer, 6-pin SOT-23	MF06A
33	FID1, FID2, FID3	0		N/A	N/A	Fiducial mark. There is nothing to buy or mount.	Fiducial

IMPORTANT NOTICE FOR TI DESIGN INFORMATION AND RESOURCES

Texas Instruments Incorporated ("TI") technical, application or other design advice, services or information, including, but not limited to, reference designs and materials relating to evaluation modules, (collectively, "TI Resources") are intended to assist designers who are developing applications that incorporate TI products; by downloading, accessing or using any particular TI Resource in any way, you (individually or, if you are acting on behalf of a company, your company) agree to use it solely for this purpose and subject to the terms of this Notice.

TI's provision of TI Resources does not expand or otherwise alter TI's applicable published warranties or warranty disclaimers for TI products, and no additional obligations or liabilities arise from TI providing such TI Resources. TI reserves the right to make corrections, enhancements, improvements and other changes to its TI Resources.

You understand and agree that you remain responsible for using your independent analysis, evaluation and judgment in designing your applications and that you have full and exclusive responsibility to assure the safety of your applications and compliance of your applications (and of all TI products used in or for your applications) with all applicable regulations, laws and other applicable requirements. You represent that, with respect to your applications, you have all the necessary expertise to create and implement safeguards that (1) anticipate dangerous consequences of failures, (2) monitor failures and their consequences, and (3) lessen the likelihood of failures that might cause harm and take appropriate actions. You agree that prior to using or distributing any applications that include TI products, you will thoroughly test such applications and the functionality of such TI products as used in such applications. TI has not conducted any testing other than that specifically described in the published documentation for a particular TI Resource.

You are authorized to use, copy and modify any individual TI Resource only in connection with the development of applications that include the TI product(s) identified in such TI Resource. NO OTHER LICENSE, EXPRESS OR IMPLIED, BY ESTOPPEL OR OTHERWISE TO ANY OTHER TI INTELLECTUAL PROPERTY RIGHT, AND NO LICENSE TO ANY TECHNOLOGY OR INTELLECTUAL PROPERTY RIGHT OF TI OR ANY THIRD PARTY IS GRANTED HEREIN, including but not limited to any patent right, copyright, mask work right, or other intellectual property right relating to any combination, machine, or process in which TI products or services are used. Information regarding or referencing third-party products or services does not constitute a license to use such products or services, or a warranty or endorsement thereof. Use of TI Resources may require a license from a third party under the patents or other intellectual property of TI.

TI RESOURCES ARE PROVIDED "AS IS" AND WITH ALL FAULTS. TI DISCLAIMS ALL OTHER WARRANTIES OR REPRESENTATIONS, EXPRESS OR IMPLIED, REGARDING TI RESOURCES OR USE THEREOF, INCLUDING BUT NOT LIMITED TO ACCURACY OR COMPLETENESS, TITLE, ANY EPIDEMIC FAILURE WARRANTY AND ANY IMPLIED WARRANTIES OF MERCHANTABILITY, FITNESS FOR A PARTICULAR PURPOSE, AND NON-INFRINGEMENT OF ANY THIRD PARTY INTELLECTUAL PROPERTY RIGHTS.

TI SHALL NOT BE LIABLE FOR AND SHALL NOT DEFEND OR INDEMNIFY YOU AGAINST ANY CLAIM, INCLUDING BUT NOT LIMITED TO ANY INFRINGEMENT CLAIM THAT RELATES TO OR IS BASED ON ANY COMBINATION OF PRODUCTS EVEN IF DESCRIBED IN TI RESOURCES OR OTHERWISE. IN NO EVENT SHALL TI BE LIABLE FOR ANY ACTUAL, DIRECT, SPECIAL, COLLATERAL, INDIRECT, PUNITIVE, INCIDENTAL, CONSEQUENTIAL OR EXEMPLARY DAMAGES IN CONNECTION WITH OR ARISING OUT OF TI RESOURCES OR USE THEREOF, AND REGARDLESS OF WHETHER TI HAS BEEN ADVISED OF THE POSSIBILITY OF SUCH DAMAGES.

You agree to fully indemnify TI and its representatives against any damages, costs, losses, and/or liabilities arising out of your non-compliance with the terms and provisions of this Notice.

This Notice applies to TI Resources. Additional terms apply to the use and purchase of certain types of materials, TI products and services. These include; without limitation, TI's standard terms for semiconductor products http://www.ti.com/sc/docs/stdterms.htm), evaluation modules, and samples (http://www.ti.com/sc/docs/sampterms.htm).

Mailing Address: Texas Instruments, Post Office Box 655303, Dallas, Texas 75265 Copyright © 2018, Texas Instruments Incorporated